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1. Name of conveying party(ies):
   KOO, Kyeong-mo
   KU, Ja-hum
   PARK, Hye-jeong
   Additional names(s) of conveying party(ies)  □ Yes  □ No

2. Name and address of receiving party(ies):
   Name: SAMSUNG ELECTRONICS CO., LTD.
   Address: 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do
   State/Prov.: 
   Country: Republic of Korea  ZIP: 
   Additional name(s) & address(es)  □ Yes  □ No

3. Nature of conveyance:
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   □ Security Agreement  □ Change of Name
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   Execution Date: FEBRUARY 13, 17, 16, 2004

4. Application number(s) or patent number(s):
   B. Patent No.(s)
   Additional numbers
   □ Yes  □ No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: ADAM C. VOLENTINE
   Registration No. 33289
   Address: VOLANTE FRANCOS, PLLC
   12200 SUNRISE VALLEY DRIVE, SUITE 150
   City: RESTON  State/Prov.: VA  ZIP: 20191
   Country: U.S.A.

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $40.00
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   MARCH 12, 2004

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PATENT
REEL: 015077 FRAME: 0771
ASSIGNMENT

In consideration of the sum of One Dollar ($1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s) of Inventor(s)  
Kyeong-mo KOO
Ja-hum KII
Hye-jeong PARK

Insert Name(s) of Assignee(s) & Address(es)  
Samsung Electronics Co., Ltd. of 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea

Title of Invention  
Method of Forming Cobalt Silicide Film and Method of Manufacturing Semiconductor Device Having Cobalt Silicide Film

Date of Signing of Application

for which an application for patent in the United States of America has been executed by the undersigned on

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.
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<th>Second Given Name</th>
<th>City</th>
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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and believe are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor: **Kyung-mo Koo**
Date: 13/02/2004

2nd Inventor: **Ja-hum Ku**
Date: 13/02/2004

3rd Inventor: **Hyung-seong PARK**
Date: 16/02/2004

4th Inventor: 
Date: 

5th Inventor: 
Date: 

6th Inventor: 
Date: 

Applicant Reference No. **SS-20288-US**
Atty Docket No. **SEC.1034/CIP**

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